



#### Description

This Bipolar Junction Transistor (BJT) is designed to meet the stringent requirements of automotive applications.

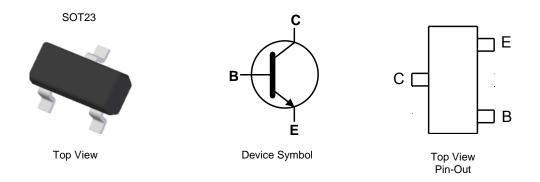
### Features

- BV<sub>CEO</sub> > 125V
- I<sub>C</sub> = 800mA High Continuous Collector Current
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

#### **125V NPN MEDIUM POWER TRANSISTOR IN SOT23**

#### **Mechanical Data**

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208<sup>(3)</sup>
- Weight 0.008 grams (Approximate)



#### Ordering Information (Note 5)

Part Number	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
BCX41QTA	Automotive	EK	7	8	3,000

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

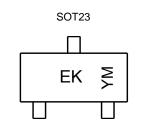
 See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to https://www.diodes.com/quality/product-compliance-definitions/.

5. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

### **Marking Information**



EK = Product Type Marking Code YM = Date Code Marking Y or  $\overline{Y}$  = Year (ex: E = 2017) M or  $\overline{M}$  = Month (ex: 9 = September)

Date Code Key

Year	2017	2018	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028
Code	E	F	G	Н	I	J	K	L	М	Ν	0	Р
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec



#### Absolute Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	125	V
Collector-Emitter Voltage	V <sub>CEO</sub>	125	V
Emitter-Base Voltage	V <sub>EBO</sub>	5	V
Continuous Collector Current	Ιc	800	mA
Peak Pulse Current	ICM	1	A
Base Current	Ι <sub>Β</sub>	100	mA

#### Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Power Dissipation	(Note 6)	D-	310	mW
Fower Dissipation	(Note 7)	PD	350	11100
Thermal Desistance, Junction to Ambient	(Note 6)	P	403	0000
Thermal Resistance, Junction to Ambient	(Note 7)	R <sub>0JA</sub>	357	°C/W
Thermal Resistance, Junction to Leads	(Note 8)	R <sub>θJL</sub>	350	°C/W
Operating and Storage Temperature Range		T <sub>J</sub> ,T <sub>STG</sub>	-55 to +150	°C

# ESD Ratings (Note 9)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

Notes: 6. For the device mounted on minimum recommended pad layout FR-4 PCB with high coverage of single sided 1oz copper in still air condition; the device is measured when operating in a steady-state condition.

7. Same as note (6), except the device is mounted on 15mm x 15mm FR-4 PCB.

8. Thermal resistance from junction to solder-point (at the end of the leads).

9. Refer to JEDEC specification JESD22-A114 and JESD22-A115.



0,1 10m

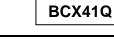
100m

1 10 Pulse Width (s)

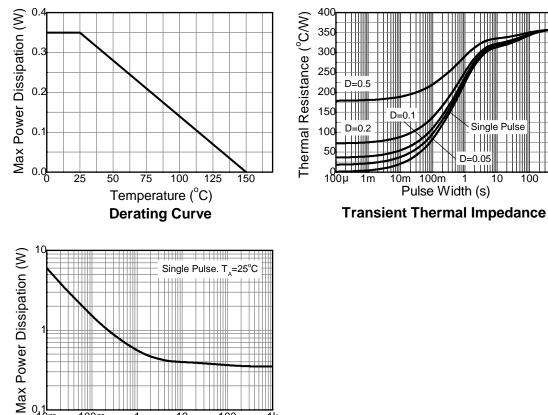
**Pulse Power Dissipation** 

100

1k



1k



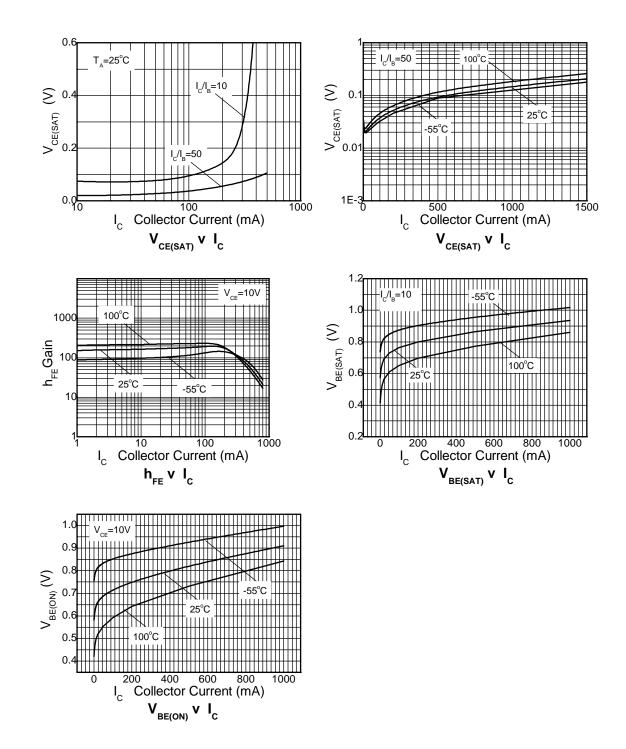


# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Emitter Breakdown Voltage	BV <sub>CES</sub>	125	—	_	V	I <sub>C</sub> = 100μA
Collector-Emitter Breakdown Voltage (Note 10)	BV <sub>CEO</sub>	125	_	_	V	I <sub>CEO</sub> = 10mA
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	7	—	_	V	I <sub>EBO</sub> = 10μA
Collector-Base Cut-Off Current	I <sub>CES</sub>	_	_	100 10	nΑ μΑ	V <sub>CB</sub> = 100V V <sub>CB</sub> = 100V, T <sub>A</sub> = +150°C
Collector Cut-Off Current	Icex	-	_	10 75	μΑ μΑ	$V_{CE} = 100V, V_{BE} = 0.2V,$ $T_A = +85^{\circ}C$ $V_{CE} = 100V, V_{BE} = 0.2V,$ $T_A = +125^{\circ}C$
Emitter-base Cut-off Current	I <sub>EBO</sub>	_	_	100	nA	V <sub>EB</sub> = 5.6V
ON CHARACTERISTICS (Note 10)						-
Static Forward Current Transfer Ratio	h <sub>FE</sub>	25 63 40	_	_	_	$\begin{split} I_{C} &= 100 \mu A, \ V_{CE} = 1 V \\ I_{C} &= 100 m A, \ V_{CE} = 1 V \\ I_{C} &= 200 m A, \ V_{CE} = 1 V \end{split}$
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>	—	—	0.9	V	I <sub>C</sub> = 300mA, I <sub>B</sub> = 30mA
Base-Emitter Saturation Voltage	V <sub>BE(SAT)</sub>	_	—	1.4	V	I <sub>C</sub> = 300mA, I <sub>B</sub> = 30mA
SMALL SIGNAL CHARACTERISTICS (Note 10)						
Transition Frequency	f⊤	—	100	—	MHz	$I_{C} = 10$ mA, $V_{CE} = 5$ V, f = 20MHz
Output Capacitance	COBO	—	12	—	pF	$V_{CB} = 10V$ , f = 1MHz

Note: 10. Measured under pulsed conditions. Pulse width  $\leq$  300µs. Duty cycle  $\leq$  2%.





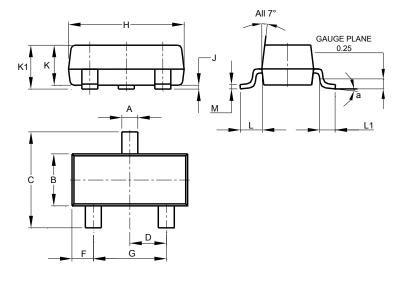


BCX41Q

### **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

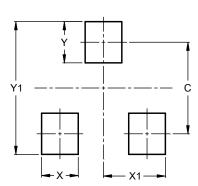
SOT23



	SOT23					
Dim	Min	Max	Тур			
Α	0.37	0.51	0.40			
В	1.20	1.40	1.30			
С	2.30	2.50	2.40			
D	0.89	1.03	0.915			
F	0.45	0.60	0.535			
G	1.78	2.05	1.83			
Н	2.80	3.00	2.90			
J	0.013	0.10	0.05			
K	0.890	1.00	0.975			
K1	0.903	1.10	1.025			
L	0.45	0.61	0.55			
L1	0.25	0.55	0.40			
Μ	0.085	0.150	0.110			
а	0°	8°				
All	Dimens	ions in	mm			

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT23

Dimensions	Value (in mm)
С	2.0
Х	0.8
X1	1.35
Y	0.9
Y1	2.9



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